Attorney Docket No.: NVID-P001125

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE Patent Application

I hereby certify	that this transmittal of the below	w described documents is being	deposited with the United Sta	ates Postal Service in an
envelope bearing	ng Express Mail Postage and a	an Express Mail label, with the t 313-1450, on the below date of d	elow serial number, addresse	d to the Commissioner
Express Mail	EV431698407US	Name of Person Making	Anthony Chou	
Label No.: Date of	02/27/04	the Deposit: Signature of the Person	11 11 2	12/11/
Deposit:		Making the Deposit:	Mondon	My Ch.
Inventor(s):	Brian S. Schi	eck and Howard Lee	e Marks	
Title:	A FLIP CHIP S AND METHOD	SEMICONDUCTOR DIE	INTERNAL SIGNAL A	CCESS SYSTEM
P.O. Box 14	ner for Patents 450 VA 22313-1450		,	
<b></b>	<u>Tra</u>	ansmittal of a Patent App (Under 37 CFR §1.53		
X Specifi Formal X Informal X Declaration Informal Form 1 X Assign X Assign	cation, claims and abst I drawings, totaling al drawings, totaling ation and Power of Atto ation Disclosure statem I 449 ment(s) ment Recordation Forn st and Certification und	orney. nent.	pages.	
	An	nendments, Priority	Claim	
35		copy has been filed in pr	is clair	rial No.
"Thi applicatio	on number onal Application	uation of and claims the	d on d on	oplication(s)

Amend this specification by inserting,	before the first line, the following sentence:					
"This application claims priority to the copending application(s)						
Serial Number	filed on					
which is hereby incorporated by reference to this specification						
International Application	filed on					
which designated the U.S."						

## **FEES DUE**

The fees due for filing the specification pursuant to 37 C.F.R. § 1.16 and for recording of the Assignment, if any, are determined as follows:

CLAIMS								
	NO. OF CLAIMS		EXTRA CLAIMS	RATE	FEES			
Basic Application	\$770.00							
Total Claims	35	Minus 20=	15	X \$18 =	\$270.00			
Independent Claims	5	Minus 3=	2	X \$86=	\$172.00			
If multiple deper	\$0.00							
Add Assignment enclosed	\$40.00							
TOTAL APPL	\$1,252.00							

## **PAYMENT OF FEES**

The full fee due in connection with this communication is provided as follows:

- 1. Not enclosed
  - [ ] No filing fee is to be paid at this time.
- 2. Enclosed
  - [X] Filing fee
  - [X] Recording assignment
  - [ X ] The Commissioner is hereby authorized to charge any additional fees associated with this communication or credit any overpayment to Deposit Account No.: 23-0085. A duplicate copy of this authorization is enclosed.
  - [X] A check in the amount of \$1,252.00

[ ] Charge any fees required or credit any overpayments associated with this filing to Deposit Account No.: 23-0085.

This application is filed pursuant to 37 C.F.R. § 1.53 in the name of the above-identified Inventor(s).

Please direct all correspondence concerning the above-identified application to the following address:

WAGNER, MURABITO & HAO LLP Two North Market Street, Third Floor San Jose, California 95113 (408) 938-9060

[X] This transmittal ends with this page.

Respectfully submitted,

Date: 2/27/04

John F. Ryan Reg. No. 47,050

Attorney Docket No.: NVID-P001125

Inventor(s):

Brian S. Schieck and Howard Lee Marks

Title:

A FLIP CHIP SEMICONDUCTOR DIE INTERNAL SIGNAL ACCESS SYSTEM

AND METHOD

## REQUEST AND CERTIFICATION UNDER 35 U.S.C. 122(b)(2)(B)(i)

I hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing. I hereby request that the attached application not be published under 35 U.S.C. 122(b).

Date:

John F. Ryan

Reg. No. 47,050

This request must be signed in compliance with 37 CFR 1.33(b) and submitted with the application **upon filing**.

Applicant may rescind this nonpublication request at any time. If applicant rescinds a request that an application not be published under U.S.C. 122(b), the application will be scheduled for publication at eighteen months from the earliest claimed filing date for which a benefit is claimed.

If applicant subsequently files an application directed to the invention disclosed in the attached application in another country, or under a multilateral international agreement, that requires publication of applications eighteen months after filing, the applicant must notify the United States Patent and Trademark Office of such filing within forty-five (45) days after the date of the filing of such foreign or international application. Failure to do so will result in abandonment of this application (35 U.S.C. 122(b)(2)(B)(iii)).